

MBRB1530CT-T, MBRB1535CT-T, MBRB1540CT-T, MBRB1545CT-T, MBRD1035CT-T,
MBRD1040CT-T, MBRD1040-T, MBRD460CT-T, MBRD835L-T

Part Number: **D2PAK See List Above**
Weight (mg): 1700

p = package designator

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon *	7440-21-3	98.90%	60.00	10.2	989000	6000
		Ni	7440-02-0	1.10%			11000	6000
Solder Paste	RoHS Exempt High Temperature	Pb	7439-92-1	92.50%	0.50	8.5	925000	4625
		Sn	7440-31-5	5.00%			50000	250
		Ag	7440-22-4	2.50%			25000	125
		Cu	7440-50-8	99.95%			999500	546327
Leadframe & Clip	Copper Alloy	Zn	7440-66-6	0.01%	54.66	929.22	60	33
		Fe	7439-89-6	0.01%			100	55
		P	7723-14-0	0.03%			340	186
		Silica (SiO ₂)	14808-60-7	75.00%			750000	324300
Encapsulation	Epoxy	Polymer with 1-chloro-2,3-epoxypropane and formaldehyde	29690-82-2	13.50%	43.24	735.08	135000	58374
		Phenol-formaldehyde polymer	9003-35-4	7.50%			75000	32430
		Sb ₂ O ₃	1309-64-4	2.50%			25000	10810
		TBBA-diglycidyl-ether oligomer	40039-93-8	1.50%			15000	6486
		Tin	7440-31-5	100.00%			1000000	10000
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.00	17	1000000	10000
Total					99.40	1700.00		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)

RoHS Exemption 7a for Pb in High Temperature, High %Pb in Solder is applied